

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the first full paragraph of page 27 with the following amended paragraph:**

(4) A method for manufacturing a wiring substrate having solder-printed layers, comprising: the step of arranging a plate-shaped mask having a plurality of through holes formed to correspond to a plurality of connection terminals, over a printed face of a substantially polygonal wiring substrate having one side of a length of at least 300 mm and having the connection terminals in the printed face; the step of forming solder-printed layers by moving a squeegee along the outer face of the mask while holding the squeegee in contact with the outer face of the mask, thereby to fill the through holes with a solder paste; and the step of detaching the mask by disengaging one side edge of the mask arranged over the printed face of the wiring substrate, relatively from the printed face, wherein the printing pressure of the squeegee is 8.5 Kgf ~~at most~~ or more. According to this method, therefore, the parting failure of the solder paste can be reliably prevented while avoiding the premature wears of parts or the breakage of the wiring substrate.

**Please replace the second full paragraph of page 30 with the following amended paragraph:**

(9) A method for manufacturing a wiring substrate having flip chip bumps, comprising: the step of arranging a plate-shaped mask having a plurality of through holes formed to correspond to a plurality of connection terminals, over a printed face of a substantially polygonal wiring substrate having one side of a length of at least 300 mm and having the

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connection terminals in the printed face covered with a solder resist having openings; the step of forming flip chip bumps protruding from the solder resist surface, by moving a squeegee at a moving speed of 20 mm/sec. at most along the outer face of the mask while holding the squeegee under a printing pressure of 7.5 Kgf ~~at most~~ or more in contact with the outer face of the mask, thereby to fill the through holes with a solder paste; and the step of detaching the mask by disengaging one side edge of the mask arranged over the printed face of the wiring substrate, relatively from the printed face.